DB2G42900L1

For rectification

■ Features

- Low forward voltage VF
- Forward current (Average) IF(AV) ≦ 1.0 A rectification is possible
- RoHS compliant (EU RoHS / MSL:Level 1 compliant)

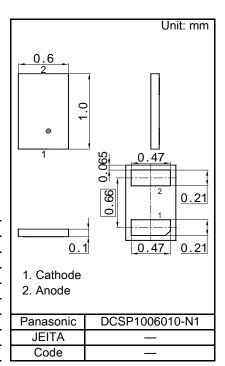
■ Marking Symbol: D5

Packaging

Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

■ Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Reverse Voltage *1	VR	-	40	V
Maximum Peak Reverse Voltage *1	VRM	-	40	V
Average Forward Current *2,3	IF(AV)	-	1.0	Α
Average Forward Current *2,4	IF(AV)	-	1.0	Α
Non-repetitive Peak Surge Forward Current *1,5	IFSM	-	15	Α
Operating Junction Temperature *6	Tj	-	150	°C
Ambient Temperature	Та	-40	+150	°C
Storage Temperature	Tstg	-55	+150	°C



Note) *1: Ta = Tj = 25°C

*2: Squre wave : $\sigma = 0.5$

*3: Ta ≤ 91°C, when device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36µm thick).

- *4: Tsp ≦ 137°C
- *5: Squre wave : Tp = 5 ms
- *6: Power derating is necessary so that Tj < 150°C.

(Waveform definition)	IF ↑ ← Tp
Duty Cycle : $\sigma = \frac{Tp}{T}$	Time
	Time

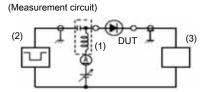
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward Voltage	VF	IF = 1.0 A	-	0.43	0.52	V
Reverse Current	IR	VR = 40 V	-	50	150	μA
Terminal Capacitance	Ct	VR = 10 V, f = 1 MHz	-	28	-	pF
Reverse Recovery Time *1	trr	IF = IR = 100 mA, Irr = 10 mA	-	8.8	-	ns

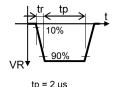
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.).

Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *1: Measurement circuit, input pulse, output pulse for Reverse recovery time



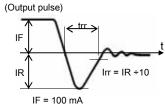
- (1) Bias Insertion Unit (N-50BU)
- (2) Pulse Generator (PG-10N), RS = 50Ω
- (3) Wave Form Analyzer (SAS-8130), Ri = 50 Ω



(Input pulse)

 $tp = 2 \mu s$ tr = 0.35 ns

 $\sigma = 0.05$

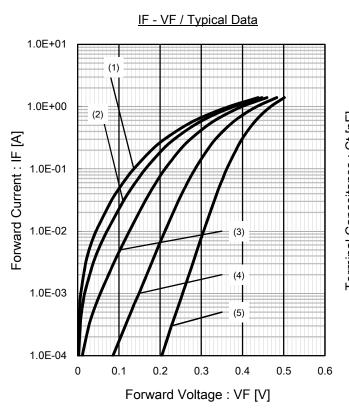


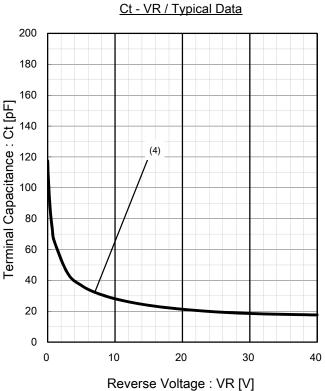
IR = 100 mA

Irr = 10 mA

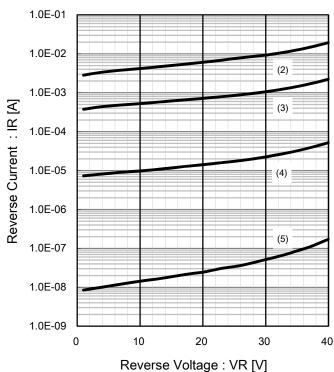
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Electrical Characteristics Technical Data (Reference)





IR - VR / Typical Data



(Graph legends)

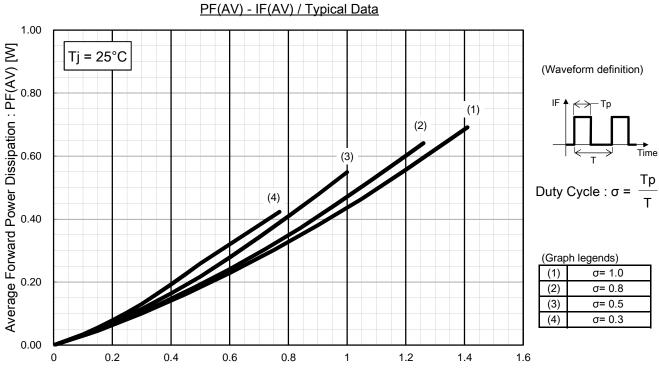
(Orap	ni icgcii	13)		
(1)	Ta =	150	°C	
(2)	Ta =	125	°C	
(3)	Ta =	85	°C	
(4)	Ta =	25	°C	
(5)	Ta =	-40	°C	

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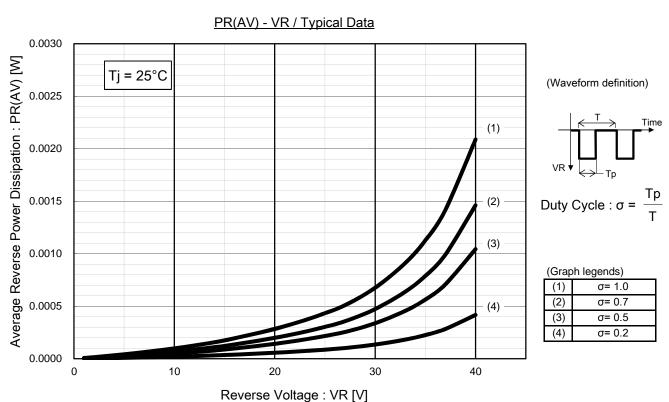
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Electrical Characteristics Technical Data (Reference)



Average Forward Current : IF(AV) [A]



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Electrical Characteristics Technical Data (Reference)

PF(AV) - IF(AV) / Typical Data 1.00 Average Forward Power Dissipation : PF(AV) [W] (Waveform definition) Tj = 150°C (1) (2) (3)Duty Cycle : $\sigma = \frac{Tp}{T}$ (4) (Graph legends) σ= 1.0 σ= 0.8 (3) σ = 0.5 $\sigma = 0.3$ 0.00 0.4 0.6 1.6

Average Forward Current : IF(AV) [A]

PR(AV) - VR / Typical Data 1.00 Average Reverse Power Dissipation: PR(AV) [W] 0.90 (Waveform definition) Tj = 125°C 0.80 (1) 0.70 0.60 (2) Duty Cycle : $\sigma = \frac{Tp}{T}$ 0.50 0.40 (3) 0.30 (Graph legends) σ= 1.0 0.20 (4) σ= 0.7 σ= 0.5 (3) 0.10 (4) σ = 0.2 0.00 10 40

Reverse Voltage: VR [V]

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Schottky Barrier Diode

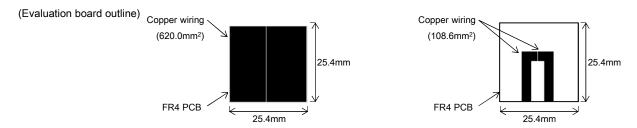
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Panasonic

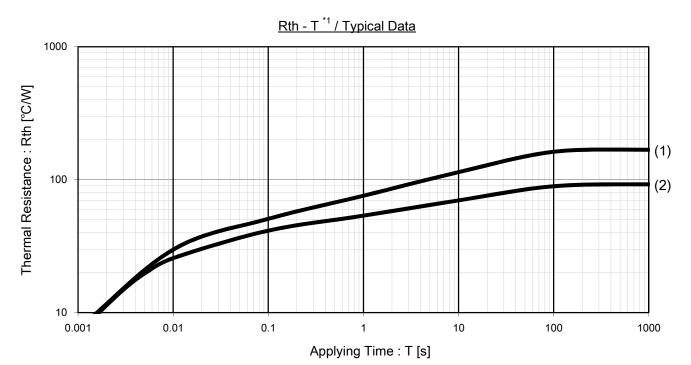
■ Thermal Characteristics

Parameter		Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction to Solder Point	$R_{th(j-sp)}$	Ta = 25°C, in free air	-	20	1	°C/W
Thermal Resistance, Junction to Ambient *1		Ta = 25°C, in free air	-	92	ı	°C/W
Thermal Resistance, Junction to Ambient *2	$R_{th(j-a)}$	Ta = 25°C, in free air	-	170	-	°C/W

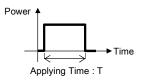
- Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36µm thick).
 - *2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.6mm² area, 36µm thick).



Thermal Characteristics Technical Data (Reference)



Note) *1: Single pulse measurement (Waveform definition)



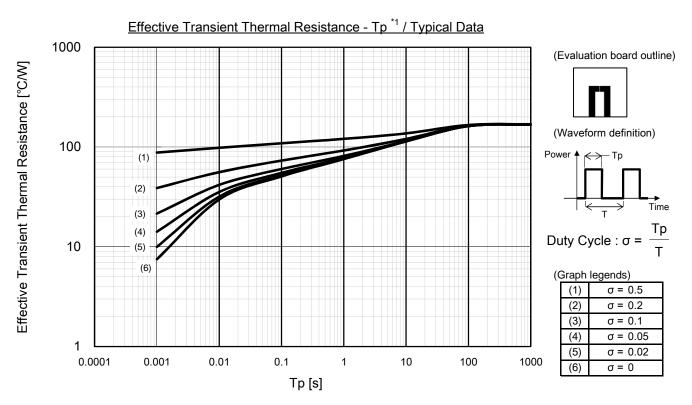
(Graph legends)

	(Graph regende)					
Γ	(1)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick),				
	(1)	copper wiring (108.6mm ² area, 36µm thick).				
Γ	(2)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick),				
L	(2)	copper wiring (620.0mm ² area, 36µm thick).				

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Thermal Characteristics Technical Data (Reference)



Effective Transient Thermal Resistance - Tp *2 / Typical Data 1000 (Evaluation board outline) Effective Transient Thermal Resistance [°C/W] (Waveform definition) 100 (1) (2) Duty Cycle : $\sigma = \frac{Tp}{T}$ (3) 10 (5) (Graph legends) $\sigma = 0.5$ $\sigma = 0.2$ (2) $\sigma = 0.1$ (3) $\sigma = 0.05$ $\sigma = 0.02$ 0.0001 0.001 0.01 0.1 1 10 100 1000 $\sigma = 0$ Tp[s]

Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.6mm² area, 36µm thick).

*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36µm thick).

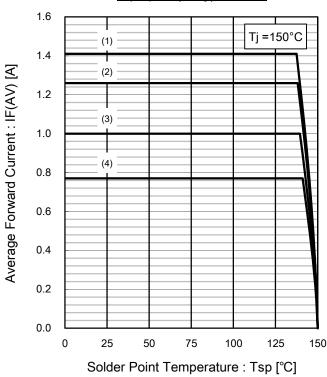
Power Derating Technical Data (Reference)

IF(AV) - Ta *1 / Typical Data 1.6 Tj =150°C (1) 1.4 Average Forward Current: IF(AV) [A] (2) 1.2 (3) 1.0 (4) 8.0 0.6 0.4 0.2 0.0 25 75 100 125 150 Ambient Temperature : Ta [°C]

1.6 Tj =150°C (1) 1.4 Average Forward Current: IF(AV) [A] (2) 1.2 (3) 1.0 (4) 8.0 0.6 0.4 0.2 0.0 25 50 75 150 100 125 Ambient Temperature : Ta [°C]

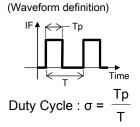
IF(AV) - Ta *2 / Typical Data

IF(AV) - Tsp / Typical Data



(Graph legends)				
(1)	σ = 1.0			
(2)	$\sigma = 0.8$			
(3)	$\sigma = 0.5$			

 $\sigma = 0.3$



Note)

(4)

*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.6mm² area, 36µm thick).

(Evaluation board outline)



*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36µm thick).

(Evaluation board outline)



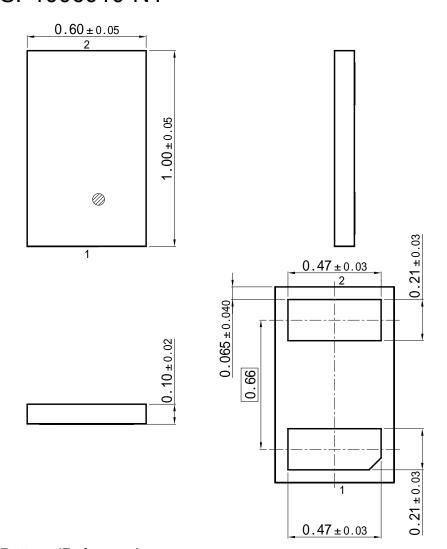
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Schottky Barrier Diode

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DCSP1006010-N1

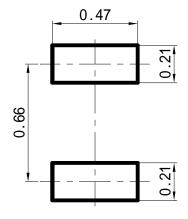
Unit: mm



■ Land Pattern (Reference)

Unit: mm

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